

Synchronous Buck NexFET™ Power Block

FEATURES

- Half-Bridge Power Block
- 90% System Efficiency at 15A
- Up To 20A Operation
- High Frequency Operation (Up To 1.5MHz)
- High Density – SON 3.3-mm × 3.3-mm Footprint
- Optimized for 5V Gate Drive
- Low Switching Losses
- Ultra Low Inductance Package
- RoHS Compliant
- Halogen Free
- Pb-Free Terminal Plating

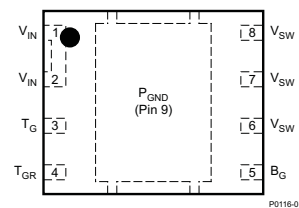
APPLICATIONS

- Synchronous Buck Converters
 - High Frequency Applications
 - High Current, Low Duty Cycle Applications
- Multiphase Synchronous Buck Converters
- POL DC-DC Converters
- IMVP, VRM, and VRD Applications

DESCRIPTION

The CSD86330Q3D NexFET™ power block is an optimized design for synchronous buck applications offering high current, high efficiency, and high frequency capability in a small 3.3-mm × 3.3-mm outline. Optimized for 5V gate drive applications, this product offers a flexible solution capable of offering a high density power supply when paired with any 5V gate drive from an external controller/driver.

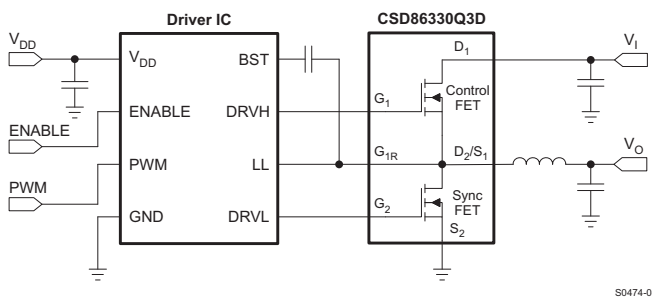
Top View



ORDERING INFORMATION

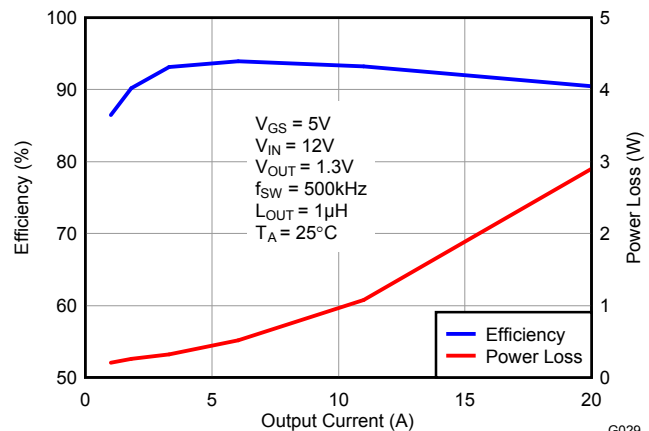
Device	Package	Media	Qty	Ship
CSD86330Q3D	SON 3.3-mm × 3.3-mm Plastic Package	13-Inch Reel	2500	Tape and Reel

TYPICAL CIRCUIT



S0474-04

TYPICAL POWER BLOCK EFFICIENCY
and POWER LOSS



G029



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NexFET is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$ (unless otherwise noted)⁽¹⁾

Parameter	Conditions	VALUE	UNIT
Voltage range	V_{IN} to P_{GND}	–0.8 to 25	V
	T_G to T_{GR}	–8 to 10	V
	B_G to P_{GND}	–8 to 10	V
Pulsed Current Rating, I_{DM}		60	A
Power Dissipation, P_D		6	W
Avalanche Energy E_{AS}	Sync FET, $I_D = 65\text{A}$, $L = 0.1\text{mH}$	211	mJ
	Control FET, $I_D = 42\text{A}$, $L = 0.1\text{mH}$	88	
Operating Junction and Storage Temperature Range, T_J , T_{STG}		–55 to 150	$^\circ\text{C}$

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

$T_A = 25^\circ$ (unless otherwise noted)

Parameter	Conditions	MIN	MAX	UNIT
Gate Drive Voltage, V_{GS}		4.5	8	V
Input Supply Voltage, V_{IN}			22	V
Switching Frequency, f_{SW}	$C_{BST} = 0.1\mu\text{F}$ (min)	200	1500	kHz
Operating Current			20	A
Operating Temperature, T_J			125	$^\circ\text{C}$

POWER BLOCK PERFORMANCE

$T_A = 25^\circ$ (unless otherwise noted)

Parameter	Conditions	MIN	TYP	MAX	UNIT
Power Loss, P_{LOSS} ⁽¹⁾	$V_{IN} = 12\text{V}$, $V_{GS} = 5\text{V}$, $V_{OUT} = 1.3\text{V}$, $I_{OUT} = 15\text{A}$, $f_{SW} = 500\text{kHz}$, $L_{OUT} = 1\mu\text{H}$, $T_J = 25^\circ\text{C}$		1.9		W
V_{IN} Quiescent Current, I_{QVIN}	T_G to $T_{GR} = 0\text{V}$ B_G to $P_{GND} = 0\text{V}$		10		μA

(1) Measurement made with six 10- μF (TDK C3216X5R1C106KT or equivalent) ceramic capacitors placed across V_{IN} to P_{GND} pins and using a high current 5V driver IC.

THERMAL INFORMATION

$T_A = 25^\circ\text{C}$ (unless otherwise stated)

THERMAL METRIC		MIN	TYP	MAX	UNIT
$R_{\theta JA}$	Junction to ambient thermal resistance (Min Cu) ⁽¹⁾			135	$^\circ\text{C/W}$
	Junction to ambient thermal resistance (Max Cu) ⁽¹⁾⁽²⁾			73	
$R_{\theta JC}$	Junction to case thermal resistance (Top of package) ⁽¹⁾			29	
	Junction to case thermal resistance (P_{GND} Pin) ⁽¹⁾			2.5	

(1) $R_{\theta JC}$ is determined with the device mounted on a 1-inch² (6.45-cm²), 2 oz. (0.071-mm thick) Cu pad on a 1.5-inch \times 1.5-inch (3.81-cm \times 3.81-cm), 0.06-inch (1.52-mm) thick FR4 board. $R_{\theta JC}$ is specified by design while $R_{\theta JA}$ is determined by the user's board design.

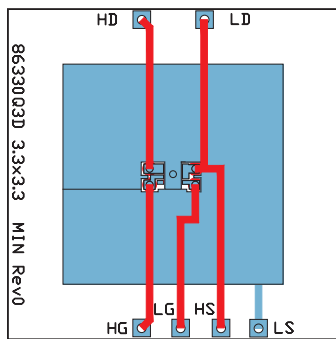
(2) Device mounted on FR4 material with 1-inch² (6.45-cm²) Cu.

ELECTRICAL CHARACTERISTICS

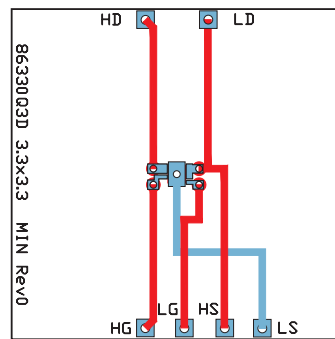
T_A = 25°C (unless otherwise stated)

PARAMETER		TEST CONDITIONS	Q1 Control FET			Q2 Sync FET			
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Static Characteristics									
BV _{DSS}	Drain to Source Voltage	V _{GS} = 0V, I _{DS} = 250μA	25			25			V
I _{DSS}	Drain to Source Leakage Current	V _{GS} = 0V, V _{DS} = 20V	1			1			μA
I _{GSS}	Gate to Source Leakage Current	V _{DS} = 0V, V _{GS} = +10 / -8	100			100			nA
V _{GS(th)}	Gate to Source Threshold Voltage	V _{DS} = V _{GS} , I _{DS} = 250μA	0.9	1.4	2.1	0.9	1.1	1.6	V
R _{DS(on)}	Drain to Source On Resistance	V _{GS} = 4.5V, I _{DS} = 14A	8.8			4.6			mΩ
		V _{GS} = 8V, I _{DS} = 14A	7.3			4.0			mΩ
g _{fs}	Transconductance	V _{DS} = 15V, I _{DS} = 14A	52			82			S
Dynamic Characteristics									
C _{ISS}	Input Capacitance ⁽¹⁾	V _{GS} = 0V, V _{DS} = 12.5V, f = 1MHz	710		920	1280		1660	pF
C _{OSS}	Output Capacitance ⁽¹⁾		350		455	680		880	pF
C _{RSS}	Reverse Transfer Capacitance ⁽¹⁾		18		23	38		49	pF
R _G	Series Gate Resistance ⁽¹⁾		1.5		3.0	1.2		2.4	Ω
Q _g	Gate Charge Total (4.5V) ⁽¹⁾	V _{DS} = 12.5V, I _{DS} = 14A	4.8		6.2	9.2		12	nC
Q _{gd}	Gate Charge - Gate to Drain		0.9			1.6			nC
Q _{gs}	Gate Charge - Gate to Source		1.6			2.1			nC
Q _{g(th)}	Gate Charge at V _{th}		0.9			1.2			nC
Q _{OSS}	Output Charge	V _{DS} = 15.5V, V _{GS} = 0V	7.2			13.6			nC
t _{d(on)}	Turn On Delay Time	V _{DS} = 12.5V, V _{GS} = 4.5V, I _{DS} = 14A, R _G = 2Ω	4.9			5.3			ns
t _r	Rise Time		7.5			6.3			ns
t _{d(off)}	Turn Off Delay Time		8.5			15.8			ns
t _f	Fall Time		1.9			4.2			ns
Diode Characteristics									
V _{SD}	Diode Forward Voltage	I _{DS} = 14A, V _{GS} = 0V	0.85		1	0.8		1	V
Q _{rr}	Reverse Recovery Charge	V _{dd} = 15.5V, I _F = 14A, di/dt = 300A/μs	3.9			7.3			nC
t _{rr}	Reverse Recovery Time		13.9			19			ns

(1) Specified by design



Max R_{θJA} = 76°C/W
when mounted on
1 inch² (6.45 cm²) of
2-oz. (0.071-mm thick)
Cu.



Max R_{θJA} = 140°C/W
when mounted on
minimum pad area of
2-oz. (0.071-mm thick)
Cu.

TYPICAL POWER BLOCK DEVICE CHARACTERISTICS

Test Conditions: $V_{IN} = 12V$, $V_{DD} = 5V$, $f_{SW} = 500kHz$, $V_{OUT} = 1.2V$, $L_{OUT} = 1.0\mu H$, $I_{OUT} = 20A$, $T_J = 125^\circ C$, unless stated otherwise.

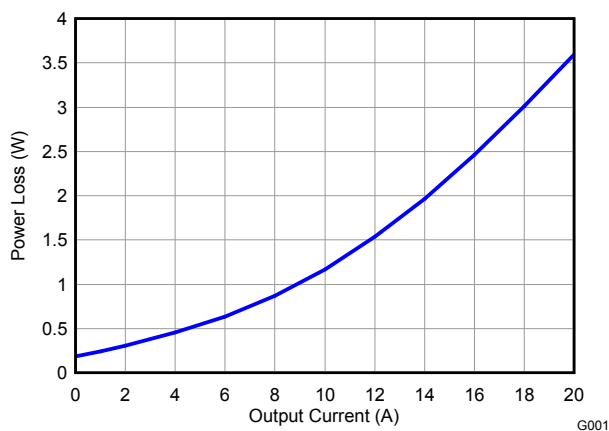


Figure 1. Power Loss vs Output Current

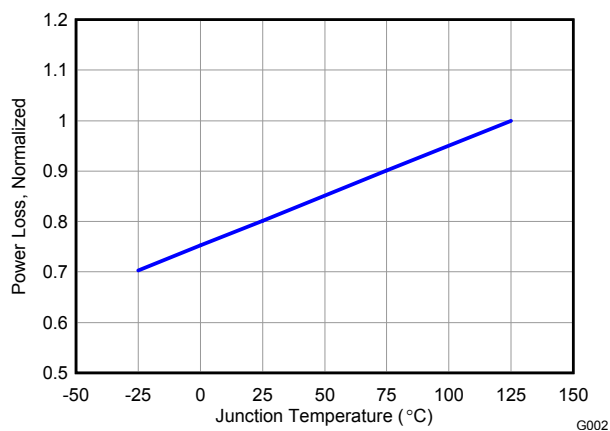


Figure 2. Power Loss vs Temperature

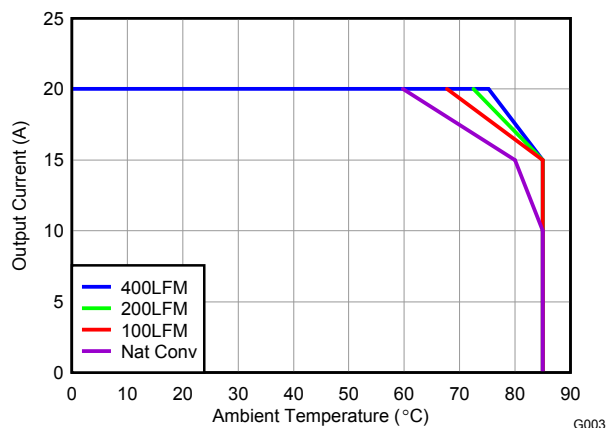


Figure 3. Safe Operating Area – PCB Vertical Mount⁽¹⁾

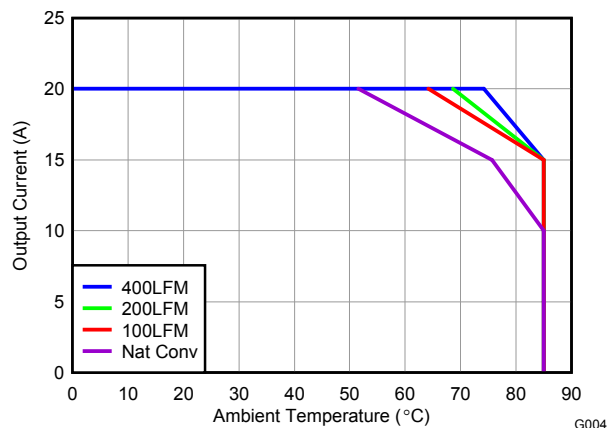


Figure 4. Safe Operating Area – PCB Horizontal Mount⁽¹⁾

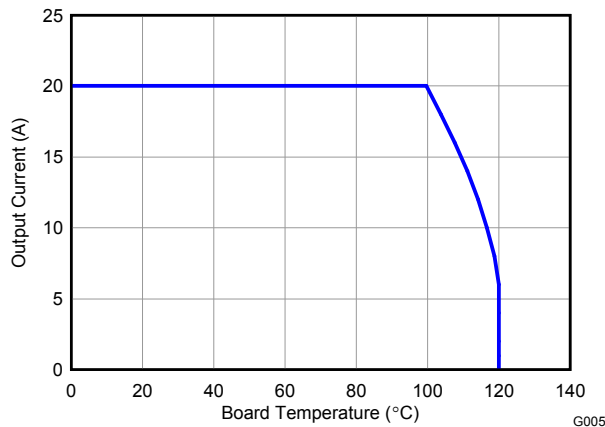


Figure 5. Typical Safe Operating Area⁽¹⁾

(1) The Typical Power Block System Characteristic curves are based on measurements made on a PCB design with dimensions of 4.0" (W) \times 3.5" (L) \times 0.062" (H) and 6 copper layers of 1 oz. copper thickness. See Application Section for detailed explanation.

TYPICAL POWER BLOCK DEVICE CHARACTERISTICS (continued)

Test Conditions: $V_{IN} = 12V$, $V_{DD} = 5V$, $f_{SW} = 500kHz$, $V_{OUT} = 1.2V$, $L_{OUT} = 1.0\mu H$, $I_{OUT} = 20A$, $T_J = 125^\circ C$, unless stated otherwise.

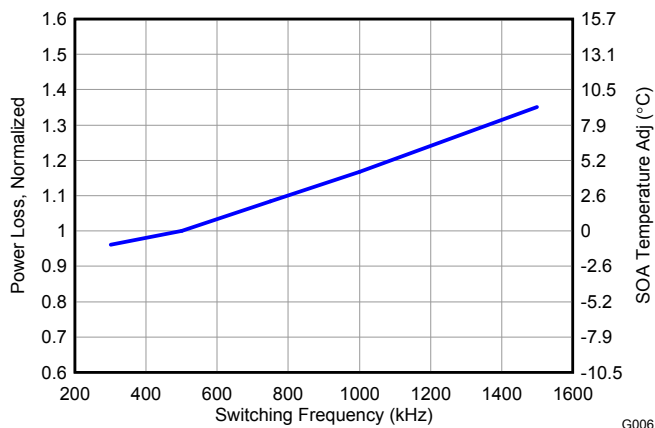


Figure 6. Normalized Power Loss vs Switching Frequency

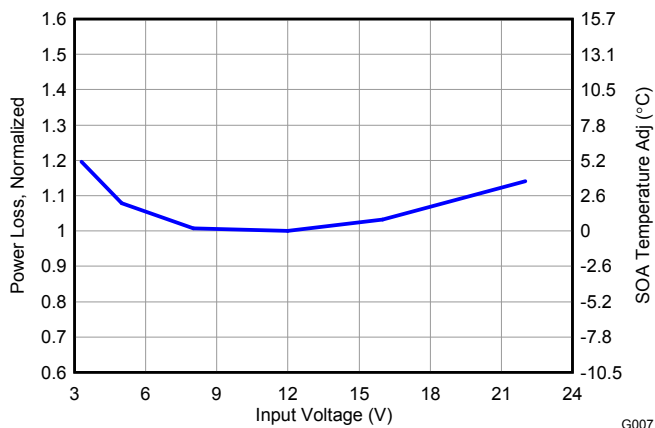


Figure 7. Normalized Power Loss vs Input Voltage

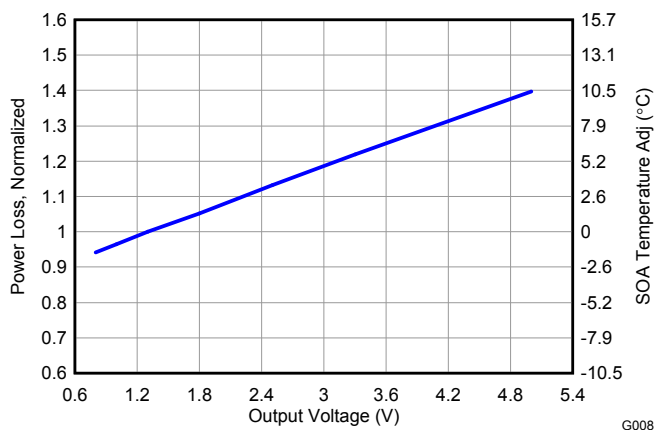


Figure 8. Normalized Power Loss vs. Output Voltage

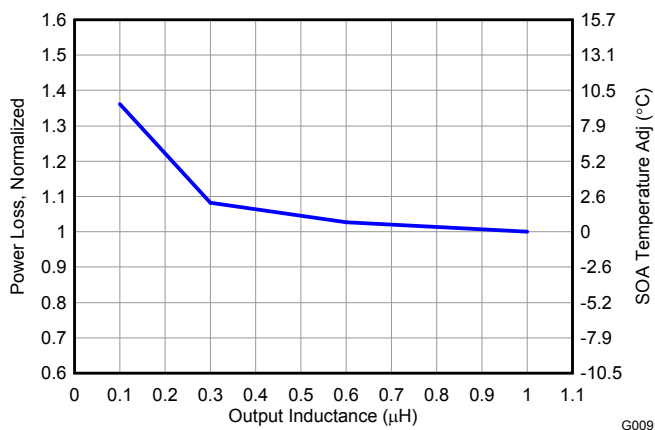


Figure 9. Normalized Power Loss vs. Output Inductance

TYPICAL POWER BLOCK MOSFET CHARACTERISTICS

$T_A = 25^\circ\text{C}$, unless stated otherwise.

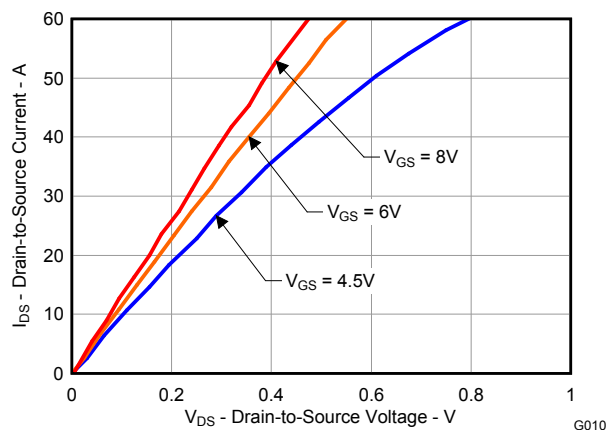


Figure 10. Control MOSFET Saturation

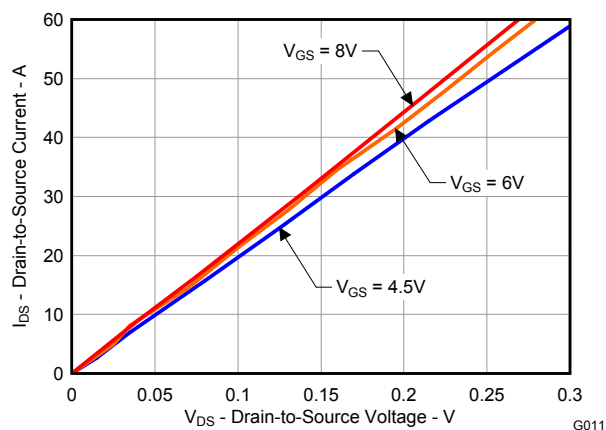


Figure 11. Sync MOSFET Saturation

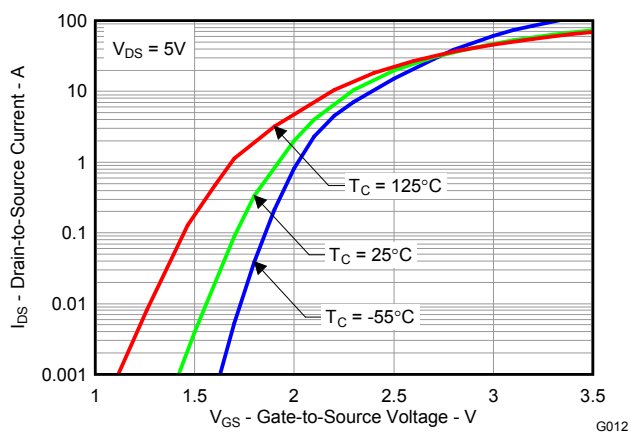


Figure 12. Control MOSFET Transfer

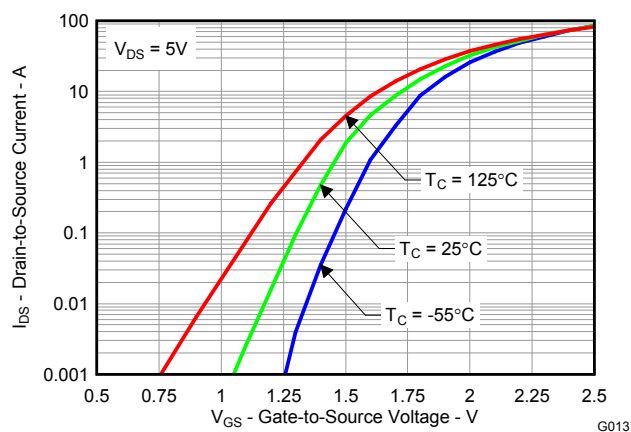


Figure 13. Sync MOSFET Transfer

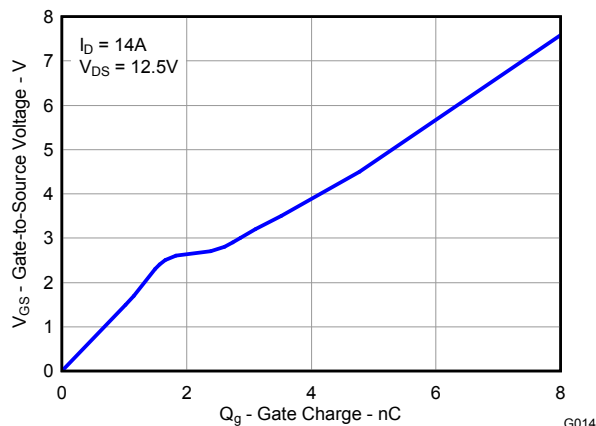


Figure 14. Control MOSFET Gate Charge

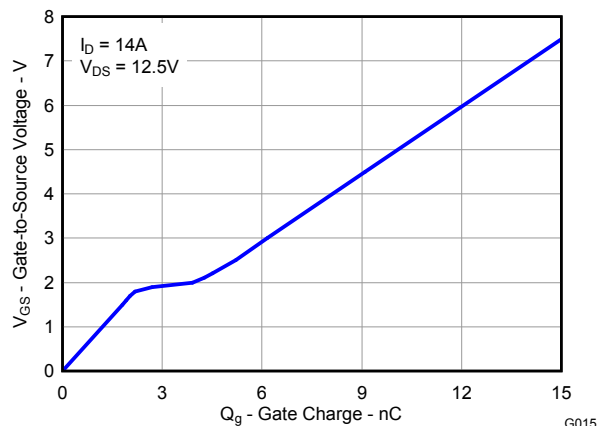


Figure 15. Sync MOSFET Gate Charge

TYPICAL POWER BLOCK MOSFET CHARACTERISTICS (continued)

$T_A = 25^\circ\text{C}$, unless stated otherwise.

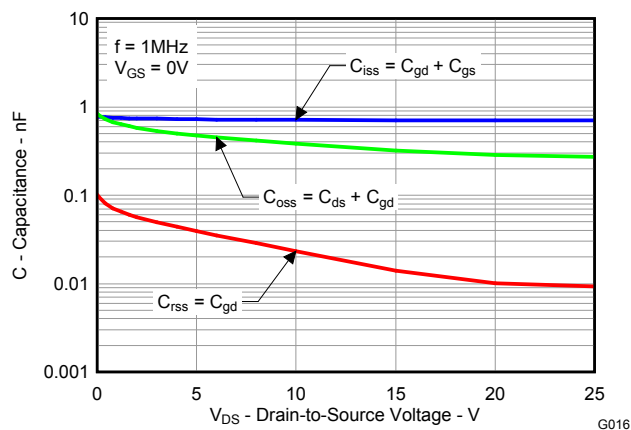


Figure 16. Control MOSFET Capacitance

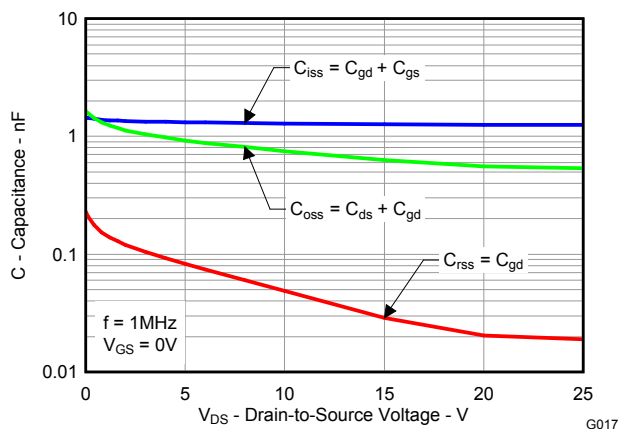


Figure 17. Sync MOSFET Capacitance

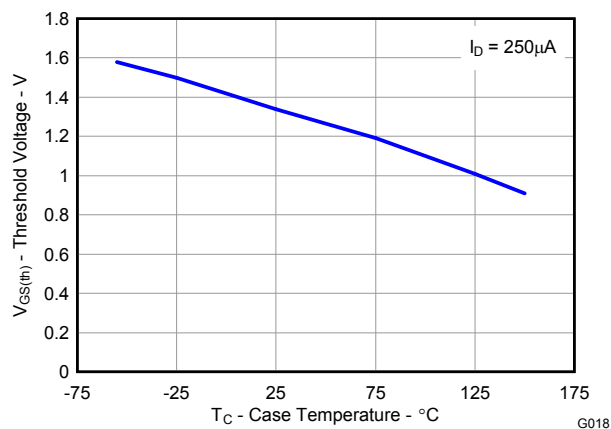


Figure 18. Control MOSFET $V_{GS(th)}$

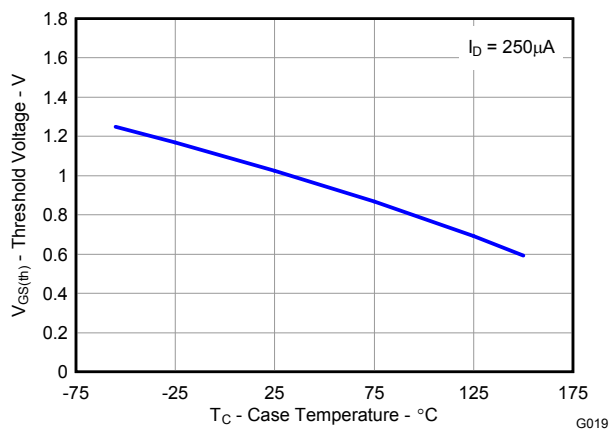


Figure 19. Sync MOSFET $V_{GS(th)}$

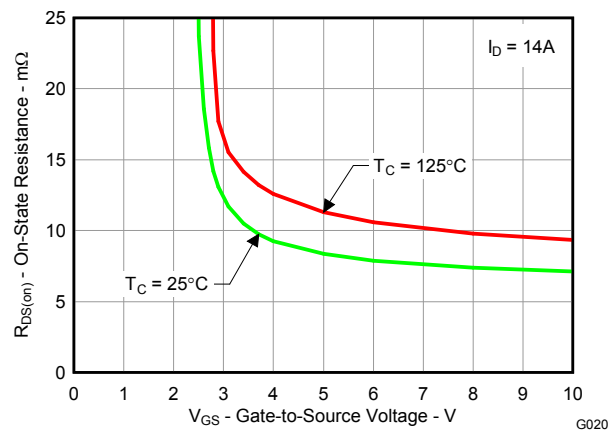


Figure 20. Control MOSFET $R_{DS(on)}$ vs V_{GS}

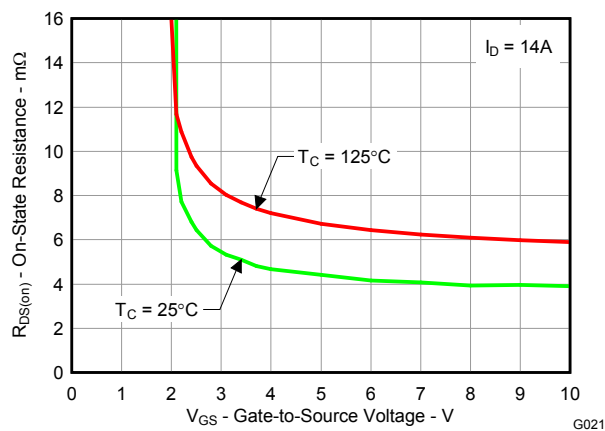


Figure 21. Sync MOSFET $R_{DS(on)}$ vs V_{GS}

TYPICAL POWER BLOCK MOSFET CHARACTERISTICS (continued)

$T_A = 25^\circ\text{C}$, unless stated otherwise.

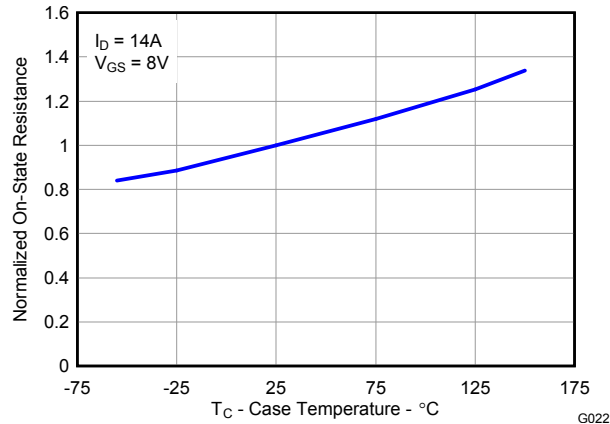


Figure 22. Control MOSFET Normalized $R_{DS(on)}$

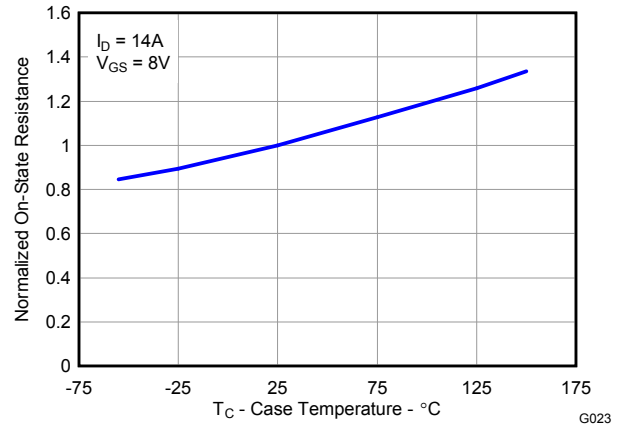


Figure 23. Sync MOSFET Normalized $R_{DS(on)}$

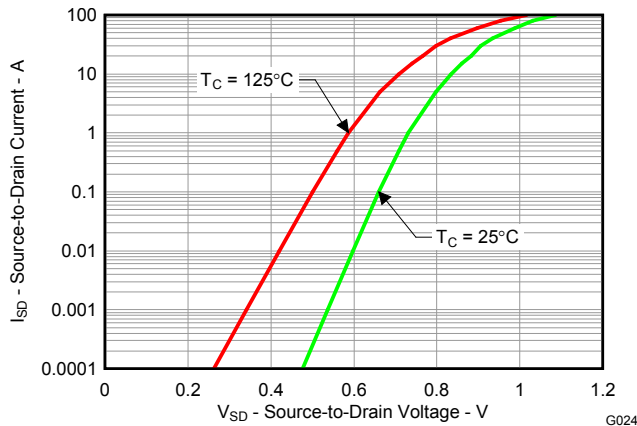


Figure 24. Control MOSFET Body Diode

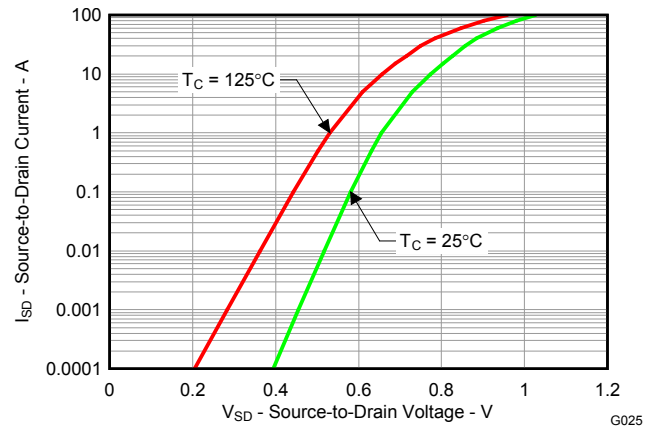


Figure 25. Sync MOSFET Body Diode

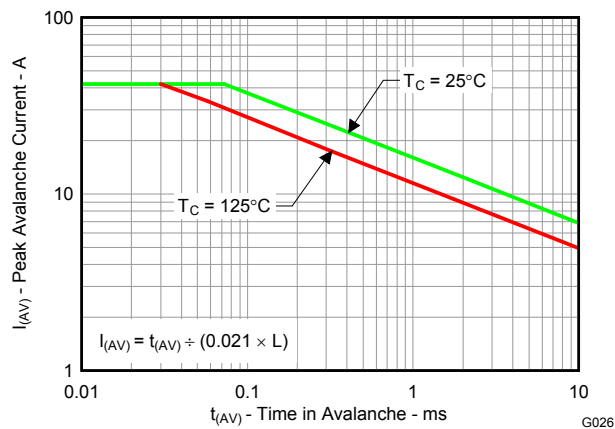


Figure 26. Control MOSFET Unclamped Inductive Switching

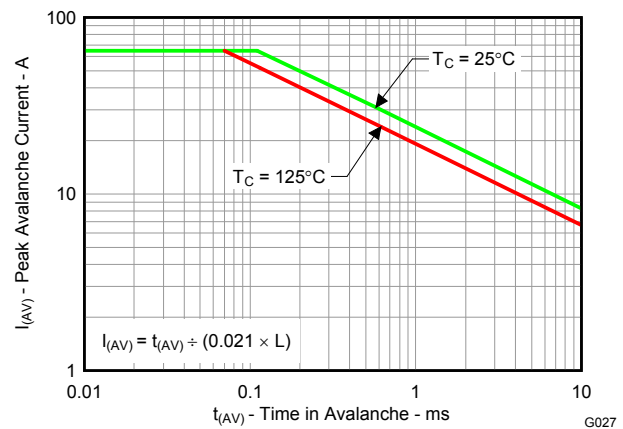


Figure 27. Sync MOSFET Unclamped Inductive Switching

APPLICATION INFORMATION

The CSD86330Q3D NexFET™ power block is an optimized design for synchronous buck applications using 5V gate drive. The Control FET and Sync FET silicon are parametrically tuned to yield the lowest power loss and highest system efficiency. As a result, a new rating method is needed which is tailored towards a more systems centric environment. System level performance curves such as Power Loss, Safe Operating Area, and normalized graphs allow engineers to predict the product performance in the actual application.

Power Loss Curves

MOSFET centric parameters such as $R_{DS(ON)}$ and Q_{gd} are needed to estimate the loss generated by the devices. In an effort to simplify the design process for engineers, Texas Instruments has provided measured power loss performance curves. Figure 1 plots the power loss of the CSD86330Q3D as a function of load current. This curve is measured by configuring and running the CSD86330Q3D as it would be in the final application (see Figure 28). The measured power loss is the CSD86330Q3D loss and consists of both input conversion loss and gate drive loss. Equation 1 is used to generate the power loss curve.

$$(V_{IN} \times I_{IN}) + (V_{DD} \times I_{DD}) - (V_{SW_AVG} \times I_{OUT}) = \text{Power Loss} \quad (1)$$

The power loss curve in Figure 1 is measured at the maximum recommended junction temperatures of 125°C under isothermal test conditions.

Safe Operating Curves (SOA)

The SOA curves in the CSD86330Q3D data sheet provides guidance on the temperature boundaries within an operating system by incorporating the thermal resistance and system power loss. Figure 3 to Figure 5 outline the temperature and airflow conditions required for a given load current. The area under the curve dictates the safe operating area. All the curves are based on measurements made on a PCB design with dimensions of 4" (W) × 3.5" (L) × 0.062" (T) and 6 copper layers of 1 oz. copper thickness.

Normalized Curves

The normalized curves in the CSD86330Q3D data sheet provides guidance on the Power Loss and SOA adjustments based on their application specific needs. These curves show how the power loss and SOA boundaries will adjust for a given set of systems conditions. The primary Y-axis is the normalized change in power loss and the secondary Y-axis is the change in system temperature required in order to comply with the SOA curve. The change in power loss is a multiplier for the Power Loss curve and the change in temperature is subtracted from the SOA curve.

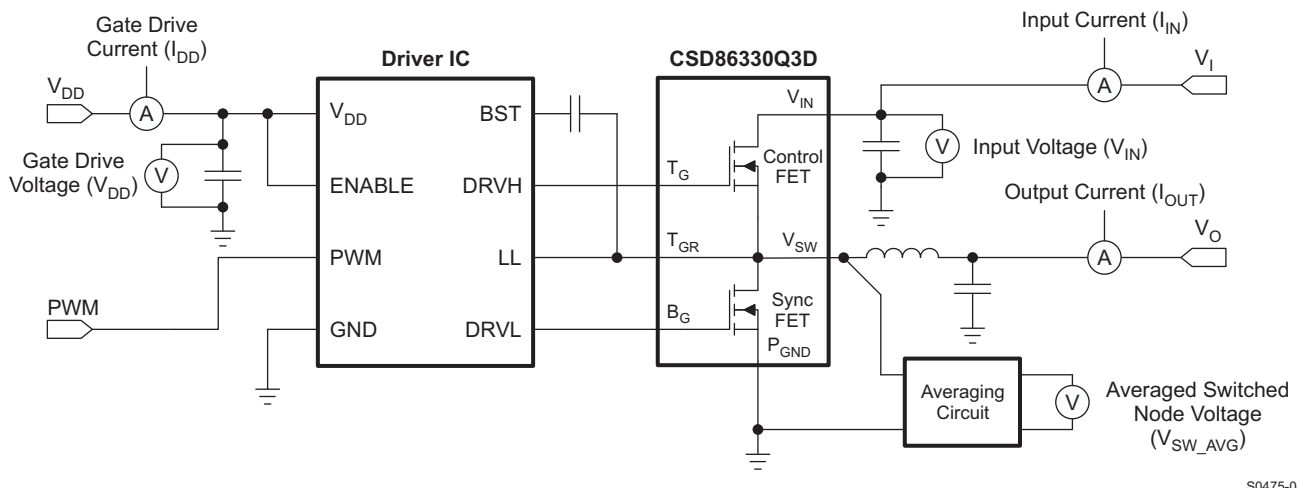


Figure 28. Typical Application

S0475-04

Calculating Power Loss and SOA

The user can estimate product loss and SOA boundaries by arithmetic means (see Design Example). Though the Power Loss and SOA curves in this data sheet are taken for a specific set of test conditions, the following procedure will outline the steps the user should take to predict product performance for any set of system conditions.

Design Example

Operating Conditions:

- Output Current = 15A
- Input Voltage = 12V
- Output Voltage = 1.2V
- Switching Frequency = 1000kHz
- Inductor = 0.4μH

Calculating Power Loss

- Power Loss at 15A = 2.2W (Figure 1)
- Normalized Power Loss for input voltage ≈ 1.0 (Figure 7)
- Normalized Power Loss for output voltage ≈ 0.98 (Figure 8)
- Normalized Power Loss for switching frequency ≈ 1.17 (Figure 6)
- Normalized Power Loss for output inductor ≈ 1.06 (Figure 9)
- **Final calculated Power Loss = $2.2W \times 1.0 \times 0.98 \times 1.17 \times 1.06 \approx 2.67W$**

Calculating SOA Adjustments

- SOA adjustment for input voltage $\approx 0^\circ\text{C}$ (Figure 7)
- SOA adjustment for output voltage $\approx -0.29^\circ\text{C}$ (Figure 8)
- SOA adjustment for switching frequency $\approx 4.1^\circ\text{C}$ (Figure 6)
- SOA adjustment for output inductor $\approx 1.5^\circ\text{C}$ (Figure 9)
- **Final calculated SOA adjustment = $0 + (-0.29) + 4.1 + 1.5 \approx 5.3^\circ\text{C}$**

In the design example above, the estimated power loss of the CSD86330Q3D would increase to 2.67W. In addition, the maximum allowable board and/or ambient temperature would have to decrease by 5.3°C . Figure 29 graphically shows how the SOA curve would be adjusted accordingly.

1. Start by drawing a horizontal line from the application current to the SOA curve.
2. Draw a vertical line from the SOA curve intercept down to the board/ambient temperature.
3. Adjust the SOA board/ambient temperature by subtracting the temperature adjustment value.

In the design example, the SOA temperature adjustment yields a reduction in allowable board/ambient temperature of 5.3°C . In the event the adjustment value is a negative number, subtracting the negative number would yield an increase in allowable board/ambient temperature.

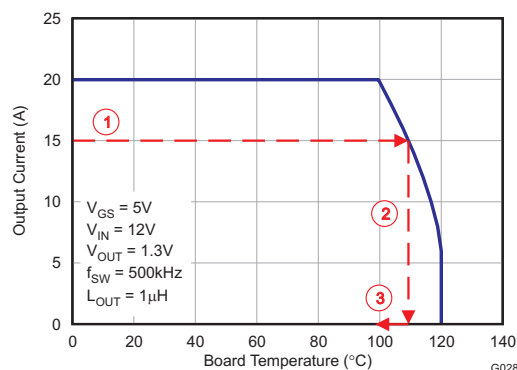


Figure 29. Power Block SOA

RECOMMENDED PCB DESIGN OVERVIEW

There are two key system-level parameters that can be addressed with a proper PCB design: Electrical and Thermal performance. Properly optimizing the PCB layout will yield maximum performance in both areas. A brief description on how to address each parameter is provided.

Electrical Performance

The Power Block has the ability to switch voltages at rates greater than 10kV/μs. Special care must be then taken with the PCB layout design and placement of the input capacitors, Driver IC, and output inductor.

- The placement of the input capacitors relative to the Power Block's VIN and PGND pins should have the highest priority during the component placement routine. It is critical to minimize these node lengths. As such, ceramic input capacitors need to be placed as close as possible to the VIN and PGND pins (see [Figure 30](#)). The example in [Figure 30](#) uses 6 × 10-μF ceramic capacitors (TDK Part # C3216X5R1C106KT or equivalent). Notice there are ceramic capacitors on both sides of the board with an appropriate amount of vias interconnecting both layers. In terms of priority of placement next to the Power Block, C5, C7, C19, and C8 should follow in order.
- The Driver IC should be placed relatively close to the Power Block Gate pins. T_G and B_G should connect to the outputs of the Driver IC. The T_{GR} pin serves as the return path of the high-side gate drive circuitry and should be connected to the Phase pin of the IC (sometimes called LX, LL, SW, PH, etc.). The bootstrap capacitor for the Driver IC will also connect to this pin.
- The switching node of the output inductor should be placed relatively close to the Power Block VSW pins. Minimizing the node length between these two components will reduce the PCB conduction losses and actually reduce the switching noise level.⁽¹⁾

Thermal Performance

The Power Block has the ability to utilize the GND planes as the primary thermal path. As such, the use of thermal vias is an effective way to pull away heat from the device and into the system board. Concerns of solder voids and manufacturability problems can be addressed by the use of three basic tactics to minimize the amount of solder attach that will wick down the via barrel:

- Intentionally space out the vias from each other to avoid a cluster of holes in a given area.
- Use the smallest drill size allowed in your design. The example in [Figure 30](#) uses vias with a 10 mil drill hole and a 16 mil capture pad.
- Tent the opposite side of the via with solder-mask.

In the end, the number and drill size of the thermal vias should align with the end user's PCB design rules and manufacturing capabilities.

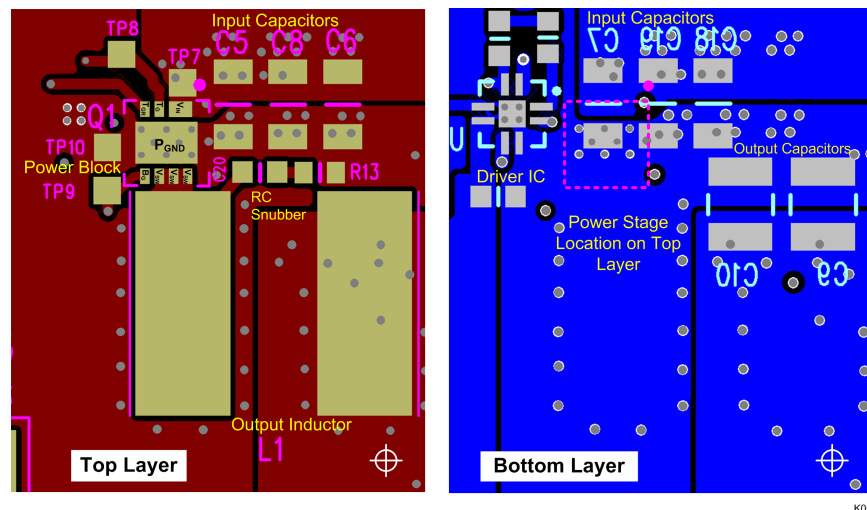
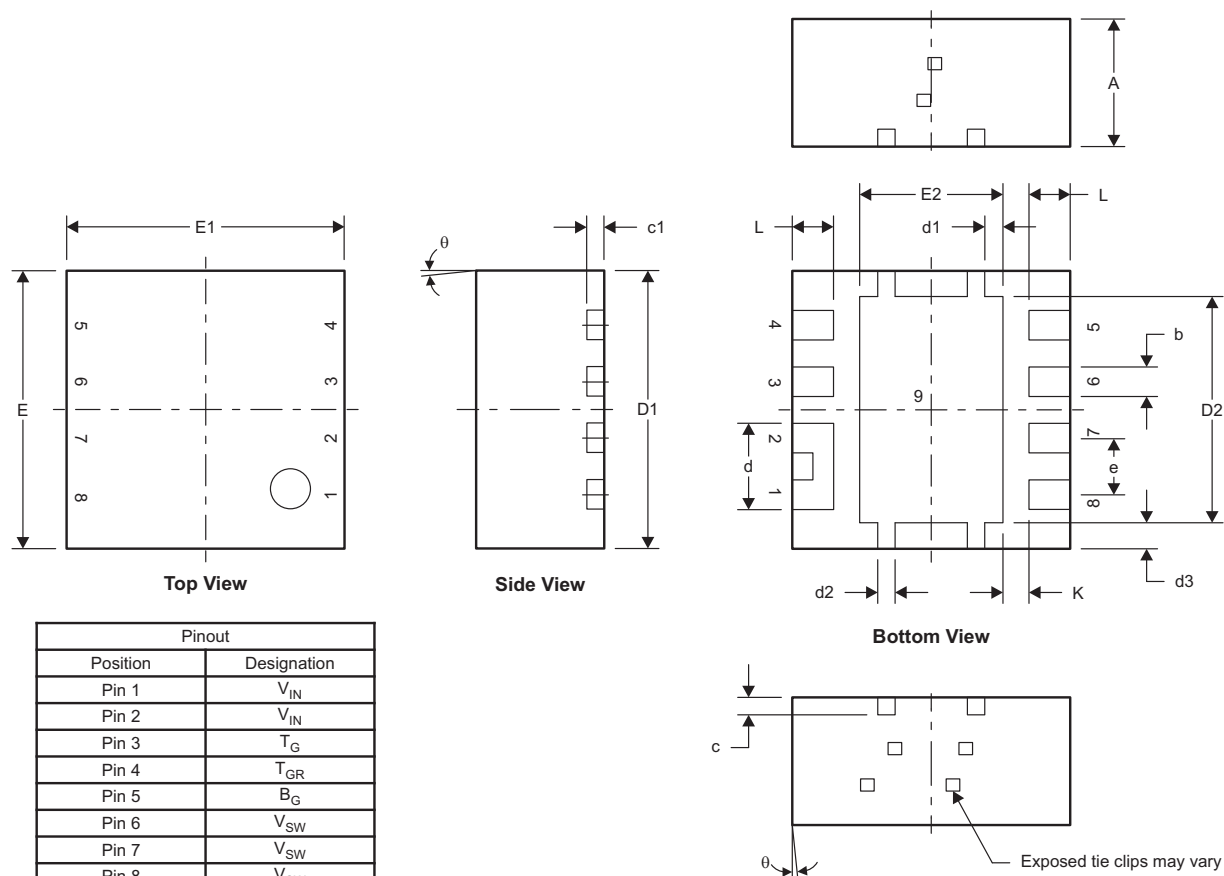


Figure 30. Recommended PCB Layout (Top Down)

(1) Keong W. Kam, David Pommerenke, "EMI Analysis Methods for Synchronous Buck Converter EMI Root Cause Analysis", University of Missouri – Rolla

MECHANICAL DATA

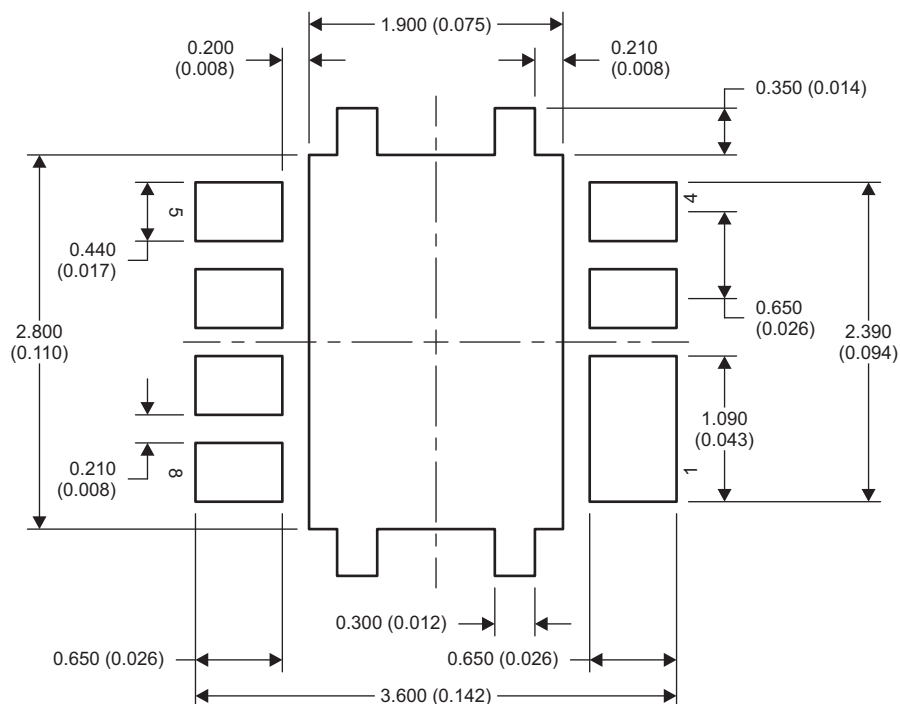
Q3D Package Dimensions



M0192-01

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
a	1.40	1.55	0.055	0.061
b	0.280	0.400	0.011	0.016
c	0.150	0.250	0.006	0.010
c1	0.150	0.250	0.006	0.010
d	0.940	1.040	0.037	0.041
d1	0.160	0.260	0.006	0.010
d2	0.150	0.250	0.006	0.010
d3	0.250	0.350	0.010	0.014
D1	3.200	3.400	0.126	0.134
D2	2.650	2.750	0.104	0.108
E	3.200	3.400	0.126	0.134
E1	3.200	3.400	0.126	0.134
E2	1.750	1.850	0.069	0.073
e	0.650 TYP		0.026 TYP	
L	0.400	0.500	0.016	0.020
θ	0.00	—	—	—
K	0.300 TYP		0.012 TYP	

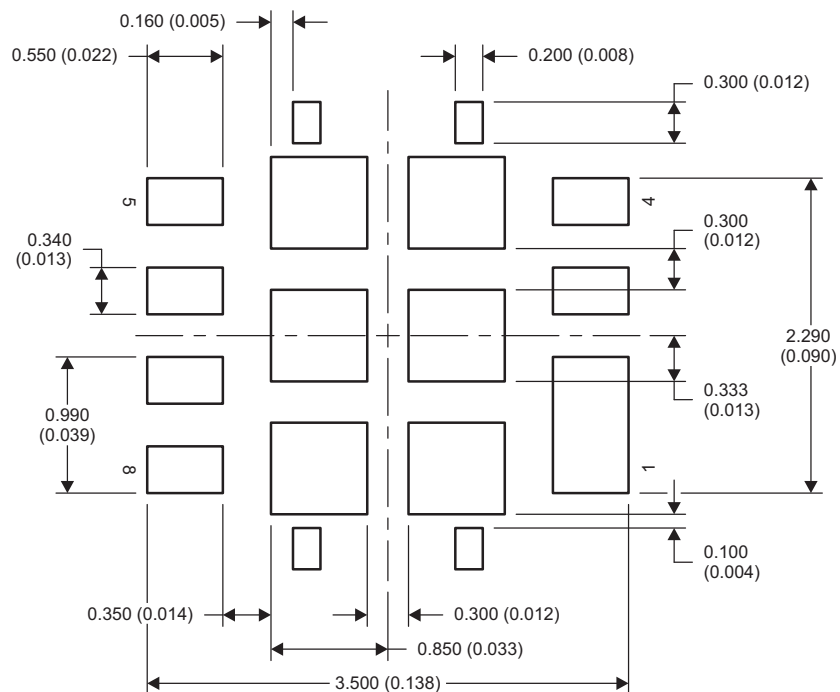
Land Pattern Recommendation



M0193-01

NOTE: Dimensions are in mm (inches).

Stencil Recommendation

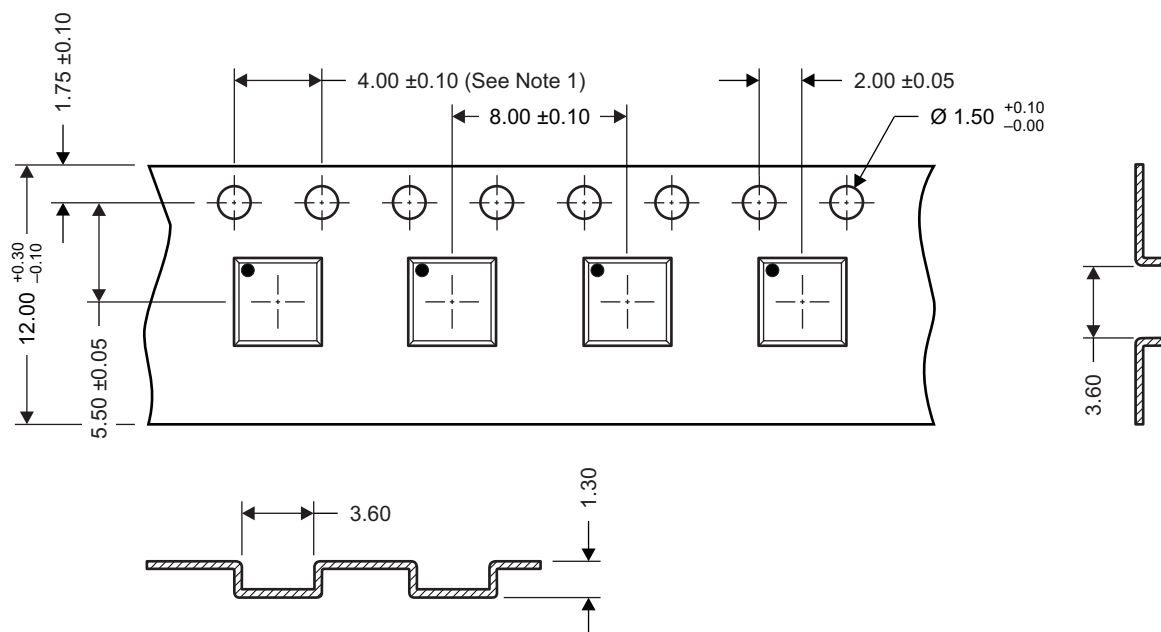


M0207-01

NOTE: Dimensions are in mm (inches).

For recommended circuit layout for PCB designs, see application note [SLPA005 – Reducing Ringing Through PCB Layout Techniques](#).

Q3D Tape and Reel Information



M0144-01

- NOTES: 1. 10-sprocket hole-pitch cumulative tolerance ± 0.2
 2. Camber not to exceed 1mm in 100mm, noncumulative over 250mm
 3. Material: black static-dissipative polystyrene
 4. All dimensions are in mm, unless otherwise specified.
 5. Thickness: 0.30 ± 0.05 mm
 6. MSL1 260°C (IR and convection) PbF reflow compatible

REVISION HISTORY

Changes from Original (October 2010) to Revision A	Page
<ul style="list-style-type: none"> Changed I_{OUT} Conditions From: 20A To: 15A, and the TYP value From: 2.9W To: 1.9W 	2

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CSD86330Q3D	ACTIVE	SON	DQZ	8	2500	Pb-Free (RoHS Exempt)	CU SN	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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